



APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	[METHOD OF RELIEVING WAFER STRESS]		
Application Type : regular, utility Attorney Docket Number : 12336-US-PA			
Correspondence address: Customer Number: 31561 			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Jui-Tsen Family Name: Huang Residence: City of Residence: Taipei Country of Residence: TW Address-1 of Mailing Address: 2F., No. 29, Alley 148, Lane 30, Yung-Chi Rd., Address-2 of Mailing Address: City of Mailing Address: Taipei State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number: 31561  as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.			